

1A, 20 - 40V Schottky Barrier Surface Mount Rectifier

FEATURES

- Plastic package has carries underwriters
- Ideal for automated placement
- Surge overload rating to 25A peak
- Reliable low cost construction utilizing molded
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Inverters
- Converters
- Adapters

MECHANICAL DATA

- Case: MELF
- Meet JESD 201 class 1A whisker test
- Polarity: Indicated by cathode band
- Weight: 120.00mg (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	1	А	
V _{RRM}	20 - 40	V	
I _{FSM}	25	А	
T _{J MAX}	125	°C	
Package	MELF		
Configuration	Single die		









ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)					
PARAMETER	SYMBOL	LL5817	LL5818	LL5819	UNIT
Repetitive peak reverse voltage	V _{RRM}	20	30	40	V
Reverse voltage, total rms value	$V_{R(RMS)}$	14	21	28	V
DC blocking voltage	V _{DC}	20	30	40	V
Forward current	I _F	1		Α	
Surge peak forward current 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	25		А	
Junction temperature	TJ	-65 to +125		°C	
Storage temperature	T _{STG}	-65 to +125		°C	



THERMAL PERFORMANCE			
PARAMETER	SYMBOL	ТҮР	UNIT
Junction-to-Ambient thermal resistance	R _{eJA}	80	°C/W

ELECTRICAL SPECIFICATIONS (T_A = 25°C unless otherwise noted)

PARAMETER		CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage ⁽¹⁾	LL5817	$I_F = 1A$		-	0.450	V
		I _F = 3A	V _F	-	0.750	V
	LL5818	I _F = 1A		-	0.550	V
		I _F = 3A		-	0.875	V
	LL5819	I _F = 1A		-	0.600	V
		I _F = 3A		-	0.900	V
Reverse current @ rated V _R ⁽²⁾		$T_J = 25^{\circ}C$	I _R	-	0.5	mA
		$T_J = 100^{\circ}C$		-	5	mA
Junction capacitance		$1 MHz, V_R = 4.0 V$	CJ	110	-	pF

Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION

ORDERING CODE ⁽¹⁾	PACKAGE	PACKING
LL581x L0G	MELF	5,000/13" reel

Notes:

1. "x" defines voltage from 20V(LL5817) to 40V(LL5819)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

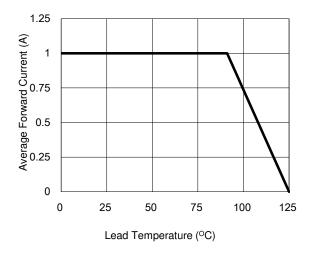


Fig.3 Typical Forward Characteristics

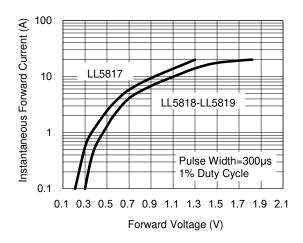


Fig.5 Typical Junction Capacitance

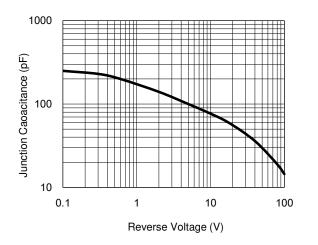
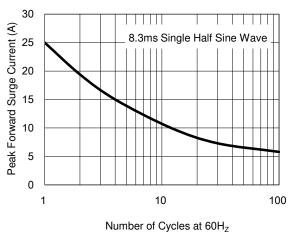


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current



Number of Cycles at ouriz

Fig.4 Typical Reverse Characteristics

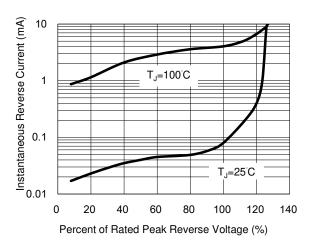
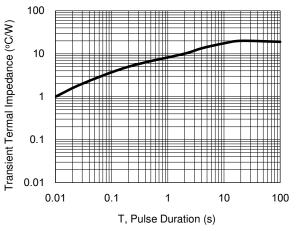


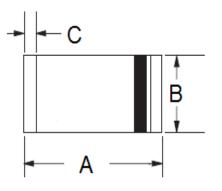
Fig.6 Typical Transient Thermal Impedance





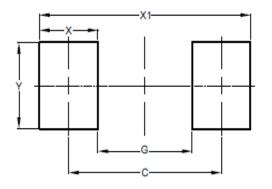
PACKAGE OUTLINE DIMENSIONS





	Unit (mm)		Unit (inch)
DIM	Min	Мах	Min	Max
Α	4.80	5.50	0.189	0.217
В	2.25	2.67	0.089	0.105
С	0.30	0.60	0.012	0.024

SUGGESTED PAD LAYOUT



DIM	Unit (mm)	Unit (inch)
DIN	ТҮР	ТҮР
С	4.80	0.189
G	3.30	0.130
Х	1.50	0.059
X1	6.30	0.248
Y	2.70	0.106



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